The **T-3002-M** is a manual, precise, high quality die bonder & component placer with superior ergonomic design and a fix die ejector needle. As with all of Tresky’s products, the **T-3002-M** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

**True Vertical Technology™**

**Unique pick-up from wafer**

**Easy to use**
Excellent performance, ergonomically designed and high reliability makes the **T-3002-M** ideal for small and medium production. Typically with a cycle time of approx. 5 sec. (process depending).

### APPLICATIONS

Die Attach, Die Sorting, Flip-Chip, MEMS, MOEMS, VCSEL, Ultrasonic, Thermosonic, RFID, Adhesive Bonding, Eutectic Bonding (AuAu, ...), ......

### FEATURES AND OPTIONS

- **TRUE VERTICAL TECHNOLOGY™**
  - Z-movement 95mm with 360° Tool rotation;
  - Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...

- **XY placement stage supporting:**
  - Waffle - / Gel - Pack -, Substrate - Holder,
  - various Heating Plates

- **Pick-up from Wafer with Tresky’s die ejector system, especially suitable for all kind of Si, GaAs and InP dies down to 30µm thickness.**

### TECHNICAL DATA

<table>
<thead>
<tr>
<th>Specification</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>XY- Movement (placement stage):</td>
<td>220mm x 220mm (manual)</td>
</tr>
<tr>
<td>XY- Movement (wafer stage):</td>
<td>220mm x 220mm (manual)</td>
</tr>
<tr>
<td>Z- Movement:</td>
<td>95mm (automatic)</td>
</tr>
<tr>
<td>Spindle Rotation:</td>
<td>360°</td>
</tr>
<tr>
<td>Max. PC Board-/ Substrate Size:</td>
<td>400mm x 280mm</td>
</tr>
<tr>
<td>Placement accuracy:</td>
<td>±10µm; ±5µm optional (process depending)</td>
</tr>
<tr>
<td>Connections:</td>
<td>Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)</td>
</tr>
<tr>
<td>Dimensions:</td>
<td>900mm x 800mm x 700mm</td>
</tr>
<tr>
<td>Weight:</td>
<td>85kg</td>
</tr>
<tr>
<td>Voltage:</td>
<td>110V / 220V</td>
</tr>
</tbody>
</table>

Note: All specifications are subject to change without notice.

### Represented by

TRUE VERTICAL TECHNOLOGY™
- Z-movement 95mm with 360° Tool rotation;
- Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...

Further Option: Flip-Chip Ultra

- Pick-up from Wafer with Tresky’s die ejector system, especially suitable for all kind of Si, GaAs and InP dies down to 30µm thickness.

---

Represented by

**Headquaters**

**www.tresky.com**

Dr. TRESKY AG
Boenirainstr. 13
CH-8800 Thalwil
Switzerland
Tel.: +41 44 772 1941
tresky@tresky.com

TRESKY Corporation
704 Ginesi Drive, Suite 11A
Morganville, NJ 07751
USA
Tel.: +1 732 536 8600
sales@tresky.com